

**N-CHANNEL ENHANCEMENT MODE FIELD MOSFET**
**Product Summary**

| $V_{(BR)SSS}$ | $R_{SS(ON)}$                   | Package      | $I_S$<br>$T_A = +25^\circ C$ |
|---------------|--------------------------------|--------------|------------------------------|
| 24V           | 26m $\Omega$ @ $V_{GS} = 4.5V$ | X1-WLB1818-4 | 6.0A                         |

**Description**

This new generation MOSFET is designed to minimize the on-state resistance ( $R_{SS(ON)}$ ) with thin WLCSP packaging process and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

**Applications**

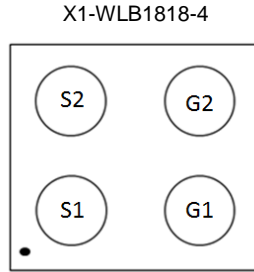
- Battery Management
- Load Switch
- Battery Protection

**Features**

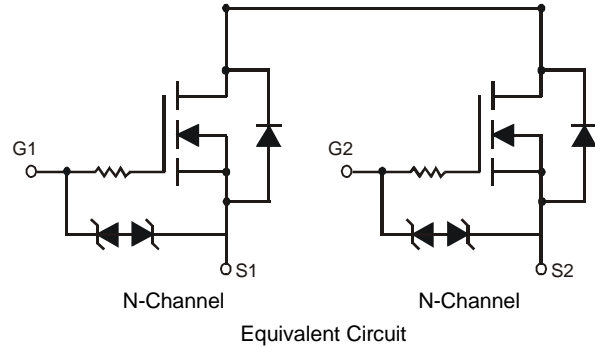
- Built-in G-S Protection Diode Against ESD 2kV HBM
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

**Mechanical Data**

- Case: X1-WLB1818-4
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram



Top View



Equivalent Circuit

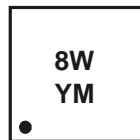
**Ordering Information** (Note 4)

| Part Number   | Case         | Packaging         |
|---------------|--------------|-------------------|
| DMN2023UCB4-7 | X1-WLB1818-4 | 3,000/Tape & Reel |

- Notes:
- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  - See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  - For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**

X1-WLB1818-4



8W = Product Type Marking Code  
 YM = Date Code Marking  
 Y or  $\bar{Y}$  = Year (ex: E = 2017)  
 M or  $\bar{M}$  = Month (ex: 9 = September)

## Date Code Key

| Year | 2011 | 2012 | 2013 | 2014 | 2015 | 2016 | 2017 |
|------|------|------|------|------|------|------|------|
| Code | Y    | Z    | A    | B    | C    | D    | E    |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code  | 1   | 2   | 3   | 4   | 5   | 6   | 7   | 8   | 9   | O   | N   | D   |

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic   |                 |                        | Symbol           | Value | Unit |
|--|-----------------|------------------------|------------------|-------|------|
| Source-Source Voltage  |                 |                        | V <sub>SSS</sub> | 24    | V    |
| Gate-Source Voltage (Note 5)                                   |                 |                        | V <sub>GSS</sub> | ±12   | V    |
| Continuous Source Current<br>@ T <sub>A</sub> = +25°C (Note 6) | Steady<br>State | T <sub>A</sub> = +25°C | I <sub>S</sub>   | 6.0   | A    |
|  |                 | T <sub>A</sub> = +70°C |                  | 4.8   |      |
| Pulsed Source Current @ T <sub>A</sub> = +25°C (Notes 6 & 7)   |                 |                        | I <sub>SM</sub>  | 20    | A    |

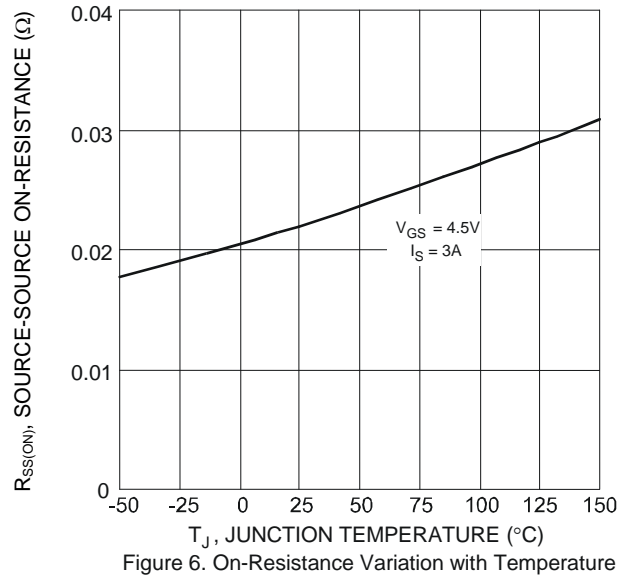
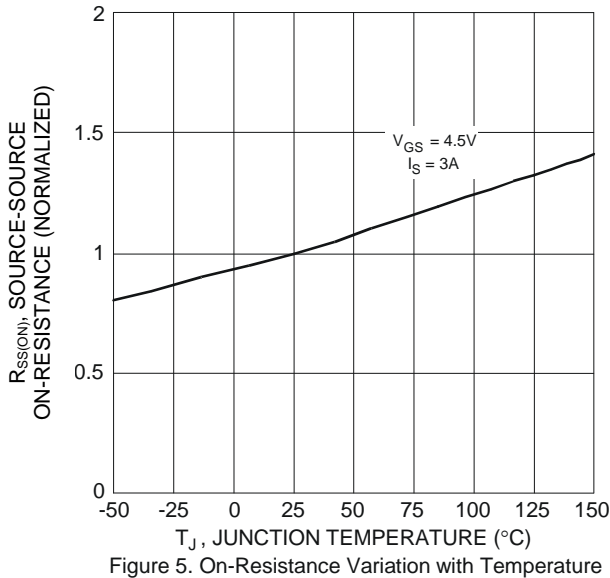
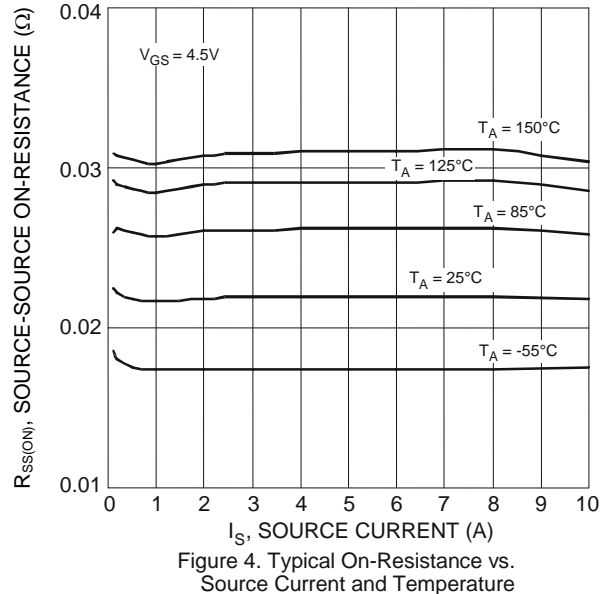
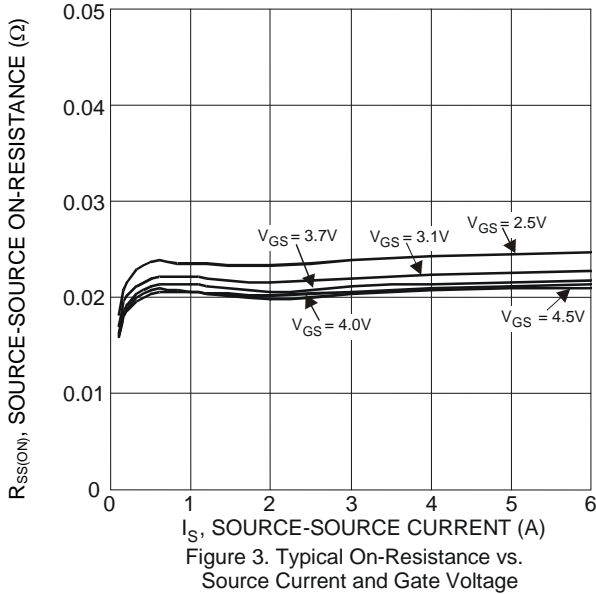
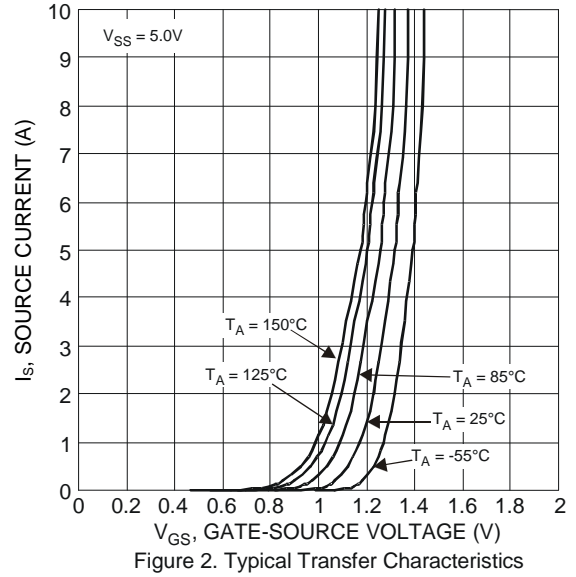
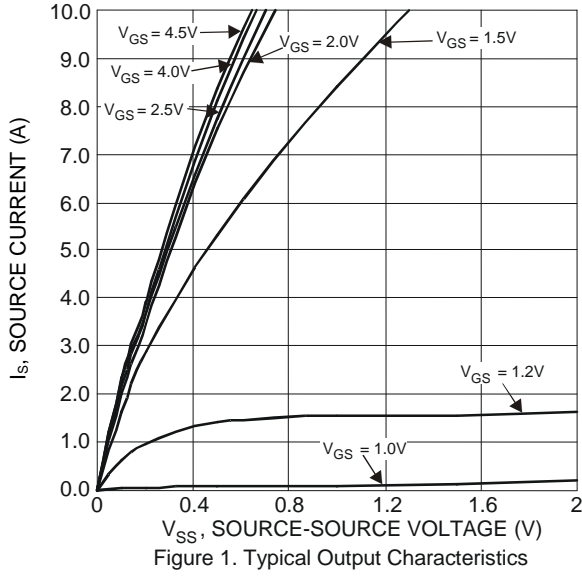
**Thermal Characteristics**

| Characteristic  | Symbol                            | Value       | Unit |
|---|-----------------------------------|-------------|------|
| Power Dissipation @ T <sub>A</sub> = +25°C (Note 6)                       | P <sub>D</sub>                    | 1.45        | W    |
| Thermal Resistance, Junction to Ambient @ T <sub>A</sub> = +25°C (Note 6) | R <sub>θJA</sub>                  | 88.21       | °C/W |
| Operating and Storage Temperature Range                                   | T <sub>J</sub> , T <sub>STG</sub> | -55 to +150 | °C   |

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic  | Symbol               | Min  | Typ  | Max  | Unit | Test Condition  |
|---|----------------------|------|------|------|------|---|
| <b>OFF CHARACTERISTICS (Note 8)</b>                       |                      |      |      |      |      |   |
| Source to Source Breakdown Voltage T <sub>J</sub> = +25°C | V <sub>(BR)SSS</sub> | 24   | —    | —    | V    | I <sub>S</sub> = 1mA, V <sub>GS</sub> = 0V, Test Circuit 1                                |
| Zero Gate Voltage Source Current T <sub>J</sub> = +25°C   | I <sub>SSS</sub>     | —    | —    | 1.0  | µA   | V <sub>SS</sub> = 20V, V <sub>GS</sub> = 0V, Test Circuit 1                               |
| Gate-Body Leakage   | I <sub>GSS</sub>     | —    | —    | ±10  | µA   | V <sub>GS</sub> = ±8V, V <sub>SS</sub> = 0V, Test Circuit 2                               |
| <b>ON CHARACTERISTICS (Note 8)</b>                        |                      |      |      |      |      |   |
| Gate Threshold Voltage                                    | V <sub>GS(TH)</sub>  | 0.5  | —    | 1.3  | V    | V <sub>SS</sub> = 10V, I <sub>S</sub> = 1.0mA, Test Circuit 3                             |
| Static Source-Source On-Resistance                        | R <sub>SS(ON)</sub>  | 17   | 21.5 | 25.5 | mΩ   | V <sub>GS</sub> = 6.5V, I <sub>S</sub> = 3.0A, Test Circuit 5                             |
|   |                      | 17.5 | 22   | 26   |      | V <sub>GS</sub> = 4.5V, I <sub>S</sub> = 3.0A, Test Circuit 5                             |
|   |                      | 18.5 | 23   | 27   |      | V <sub>GS</sub> = 4.0V, I <sub>S</sub> = 3.0A, Test Circuit 5                             |
|   |                      | 19   | 23.5 | 29   |      | V <sub>GS</sub> = 3.7V, I <sub>S</sub> = 3.0A, Test Circuit 5                             |
|   |                      | 19.5 | 24   | 33   |      | V <sub>GS</sub> = 3.1V, I <sub>S</sub> = 3.0A, Test Circuit 5                             |
|   |                      | 21.5 | 27   | 40   |      | V <sub>GS</sub> = 2.5V, I <sub>S</sub> = 3.0A, Test Circuit 5                             |
| Forward Transfer Admittance                               | Y <sub>fs</sub>      | —    | 12   | —    | S    | V <sub>SS</sub> = 10V, I <sub>S</sub> = 3.0A, Test Circuit 4                              |
| Body Diode Forward Voltage                                | V <sub>F(S-S)</sub>  | —    | 0.7  | 1    | V    | I <sub>F</sub> = 3.0A, V <sub>GS</sub> = 0V, Test Circuit 6                               |
| <b>DYNAMIC CHARACTERISTICS (Note 9)</b>                   |                      |      |      |      |      |   |
| Input Capacitance   | C <sub>iss</sub>     | —    | 2564 | 3333 | pF   | V <sub>SS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1.0MHz<br>Test Circuit 7                 |
| Output Capacitance  | C <sub>oss</sub>     | —    | 197  | 275  |      |   |
| Reverse Transfer Capacitance                              | C <sub>riss</sub>    | —    | 183  | 260  |      |   |
| Total Gate Charge   | Q <sub>g</sub>       | —    | 29   | 37   | nC   | V <sub>GS</sub> = 4.5V, V <sub>SS</sub> = 10V, I <sub>S</sub> = 6A<br>Test Circuit 9      |
| Turn-On Delay Time  | t <sub>D(ON)</sub>   | —    | 10   | 15   | ns   | V <sub>SS</sub> = 10V,<br>R <sub>L</sub> = 3.33Ω, I <sub>S</sub> = 3.0A<br>Test Circuit 8 |
| Turn-On Rise Time   | t <sub>R</sub>       | —    | 20   | —    | ns   |   |
| Turn-Off Delay Time                                       | t <sub>D(OFF)</sub>  | —    | 75   | 110  | ns   |   |
| Turn-Off Fall Time  | t <sub>F</sub>       | —    | 29   | —    | ns   |   |

- Notes:
- AEC-Q101 V<sub>GS</sub> maximum is ±9.6V.
  - Device mounted on FR-4 material with 1-inch<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz.(0.071-mm thick) Cu.
  - Repetitive rating, pulse width limited by junction temperature.
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to production testing.



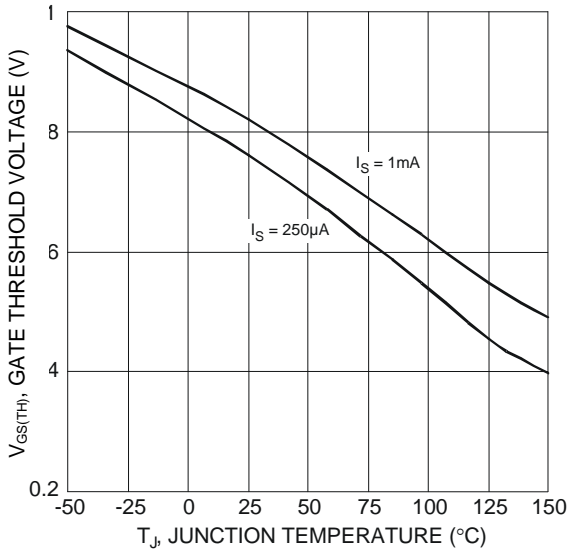


Figure 7. Gate Threshold Variation vs. Junction Temperature

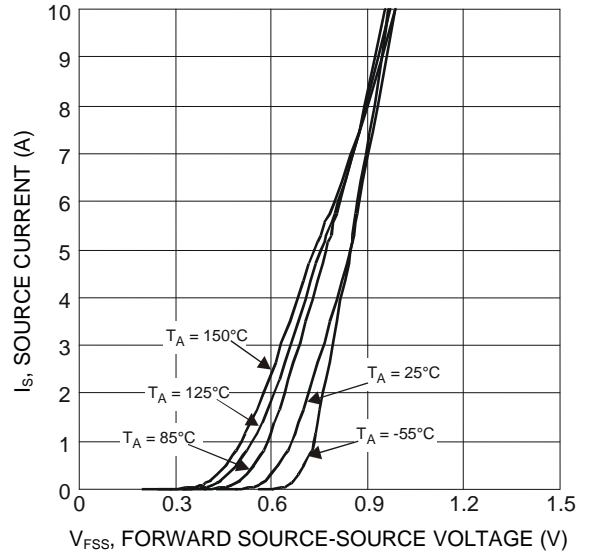


Figure 8. Diode Forward Voltage vs. Current

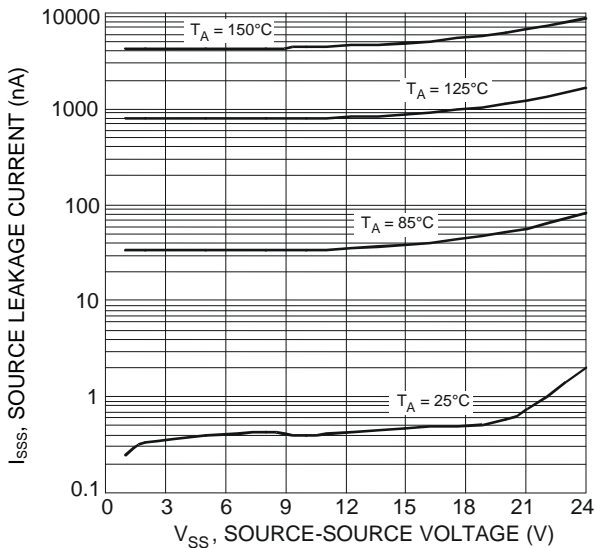


Figure 9. Typical Source-Source Leakage Current vs. Voltage

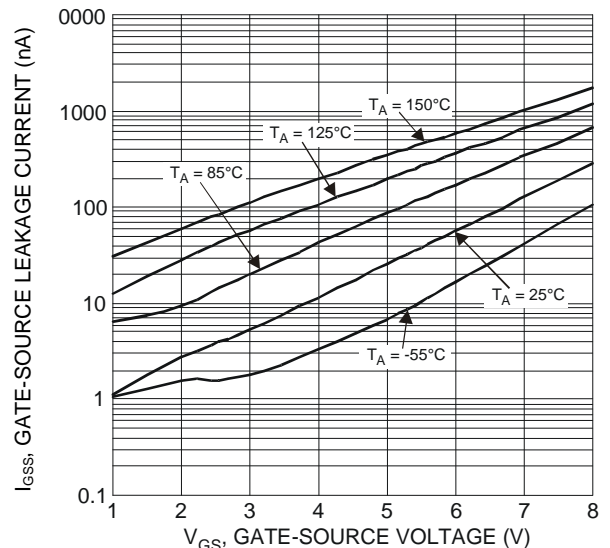


Figure 10. Typical Gate-Source Leakage Current vs. Gate-Source Voltage

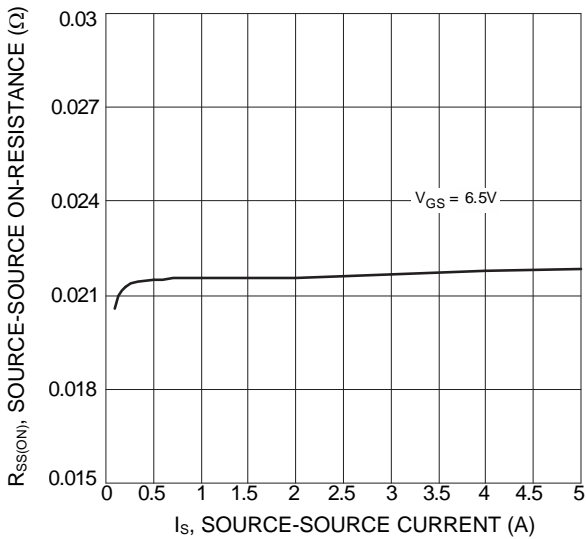


Figure 11. Typical On-Resistance vs. Source Current and Gate Voltage

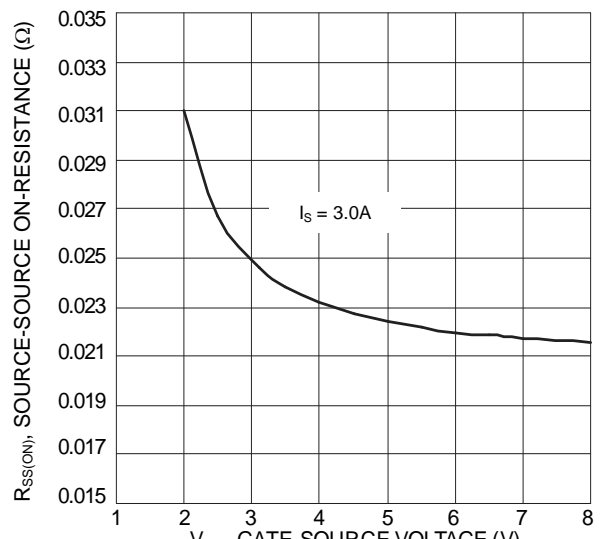
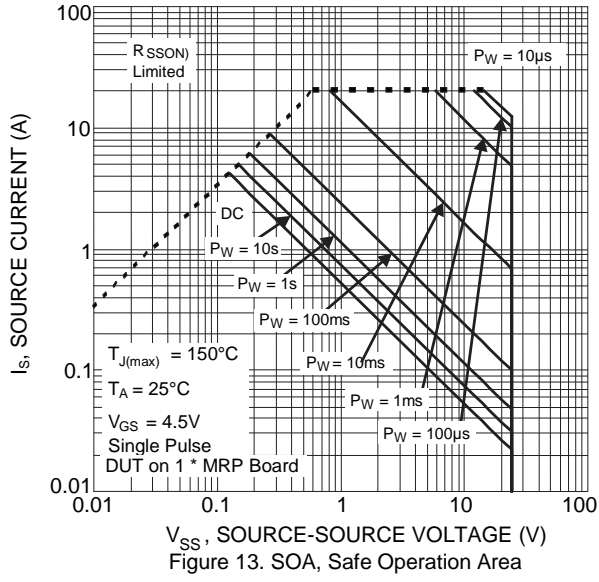
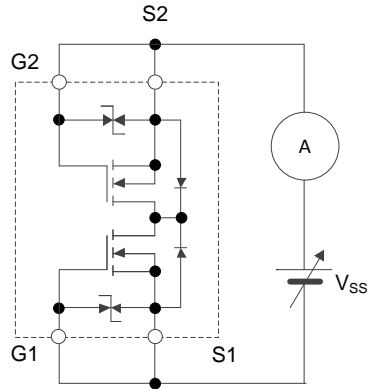


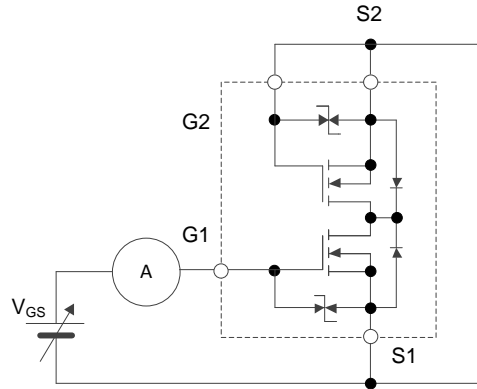
Figure 12. Typical Transfer Characteristic



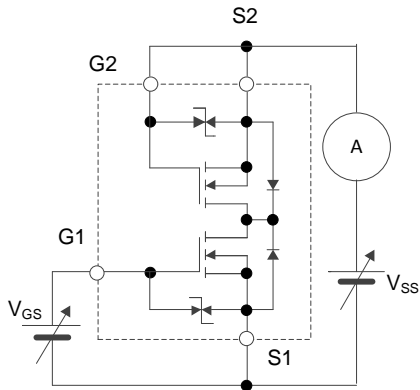
**Test Circuits**



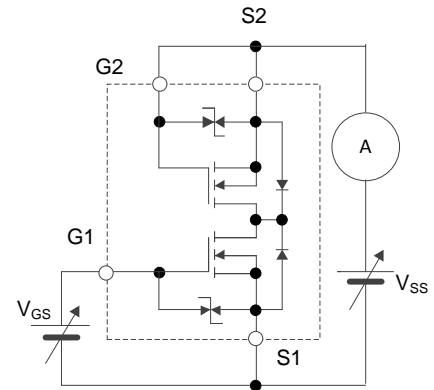
Test Circuit 1  $I_{SSS}$



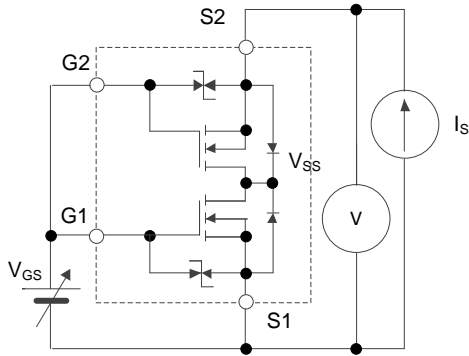
Test Circuit 2  $I_{GSS}$   
When FET1 is measured, between GATE and SOURCE of FET2 are shorted.



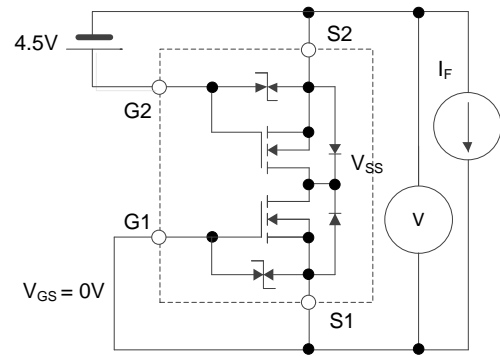
Test Circuit 3  $V_{GS(OFF)}$   
When FET1 is measured, between GATE and SOURCE of FET2 are shorted.



Test Circuit 4  $|Y_{fs}|$   
 $\Delta I_S / \Delta V_{GS}$

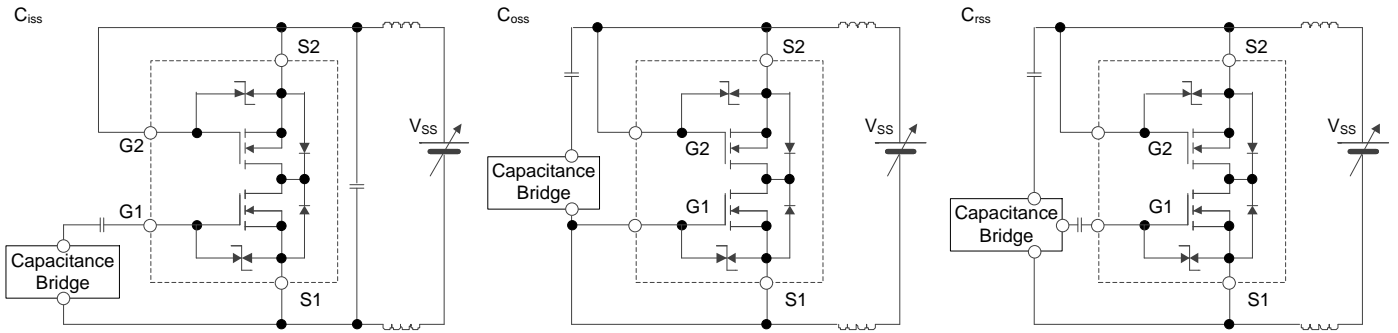


Test Circuit 5  $R_{SS(ON)}$   
 $V_{SS}/I_S$

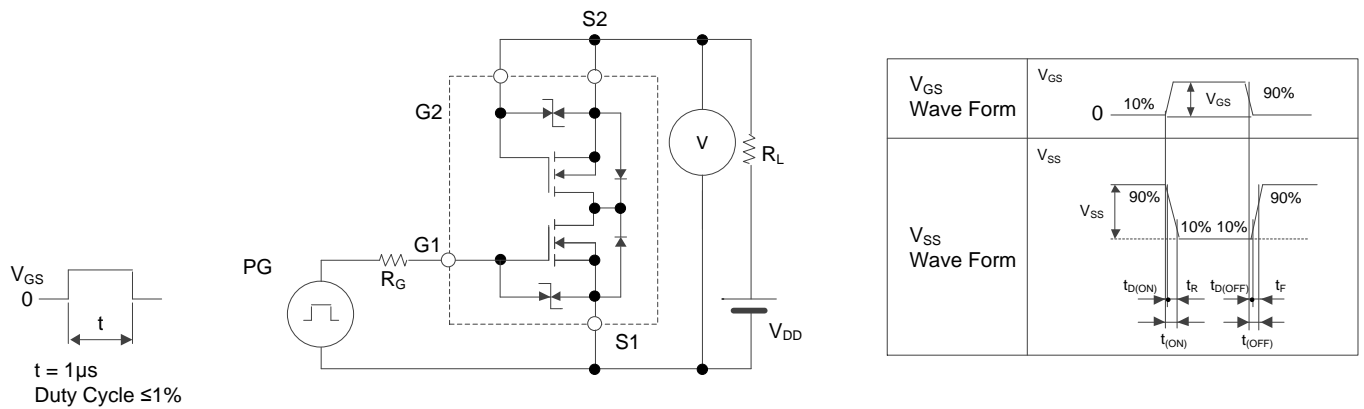


Test Circuit 6  $V_{F(S-S)}$   
When FET1 is measured, FET2 is added  $V_{GS} + 4.5V$ .

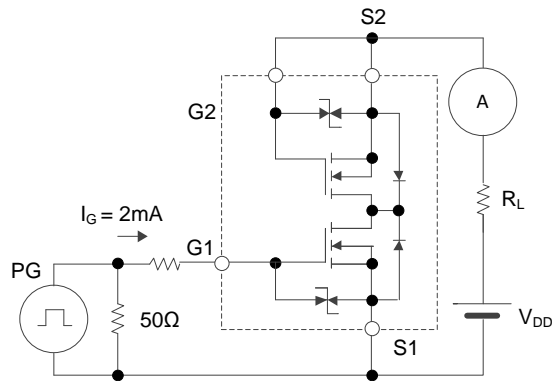
**Test Circuits (Cont.)**



Test Circuit 7



Test Circuit 8  $t_{D(ON)}$ ,  $t_R$ ,  $t_{D(OFF)}$ ,  $t_F$

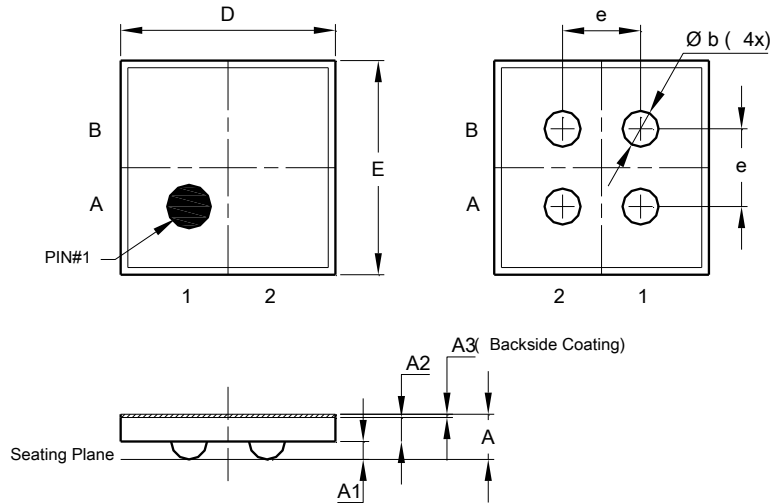


Test Circuit 9  $Q_G$

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-WLB1818-4

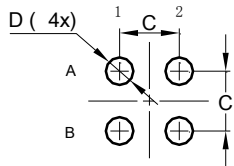


| X1-WLB1818-4                |           |        |        |
|-----------------------------|-----------|--------|--------|
| Dim                         | Min       | Max    | Typ    |
| A                           | 0.3420    | 0.4080 | 0.3750 |
| A1                          | 0.1350    | 0.1650 | 0.1500 |
| A2                          | 0.1850    | 0.2150 | 0.2000 |
| A3                          | 0.0220    | 0.0280 | 0.0250 |
| b                           | 0.2700    | 0.3300 | 0.3000 |
| D                           | 1.7800    | 1.8000 | 1.7900 |
| E                           | 1.7800    | 1.8000 | 1.7900 |
| e                           | 0.650 BSC |        |        |
| <b>All Dimensions in mm</b> |           |        |        |

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-WLB1818-4



| Dimensions | Value (in mm) |
|------------|---------------|
| C          | 0.65          |
| D          | 0.30          |



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